

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**APPLICANT** ECKMILLER, ROLF ET AL.

**TITLE** MICROCONTACT STRUCTURE FOR NEUROPROSTHESES  
FOR IMPLANTATION ON NERVE TISSUE AND METHOD  
THEREFOR

**FILING DATE** Herewith

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Honorable Assistant Commissioner of Patents and Trademarks, Box Patent Applications, Washington, D.C. 20231

Date of Deposit: *Jan. 26, 2001*

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Signature: *Richard C. Woodbridge*

Date of Signature: *Jan. 26, 2001*

**HONORABLE ASSISTANT COMMISSIONER OF PATENTS  
BOX PATENT APPLICATIONS  
WASHINGTON, D.C. 20231**

**PRELIMINARY AMENDMENT**

Dear Sir:

Preliminary to a First Office Action on the merits of this application please amend the application as follows:

**IN THE SPECIFICATION:**

Page 3, line 25 please add the following:

**BRIEF DESCRIPTION OF THE DRAWINGS**

Figs. 1a-1c illustrate the manner in which the microcontact structure can be folded.

*A1*

Fig. 1d illustrates the manner in which the folded structure can be clamped in place.